EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	72	(first near2 (chip die device semiconductor)) with (adhesive underfill (under adj fill)) with (inject$3 introduc$3) with between	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 11:57
L5	1409	(inject$3 introduc$3) with (underfill (under adj fill) adhesive (bonding adj (material paste resin))) with (push$3 away forc$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 13:42
L6	1	5 with (first near2 (chip die device semiconductor)) with (second near2 (chip die device semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 13:43
L7	3628	((inject$3 introduc$3) with (underfill (under adj fill) adhesive (bonding adj (material paste resin)))) same (push$3 away forc$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 14:04
L8	11	7 same ((first near2 (chip die device semiconductor)) with (second near2 (chip die device semiconductor)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 14:04
L12	7111	((inject$3 dispens$3 introduc$3) with (underfill (under adj fill) adhesive (bonding adj (material paste resin)))) same (push$3 away forc$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 14:04
L13	48	12 same (second near2 (chip die device semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/14 14:05